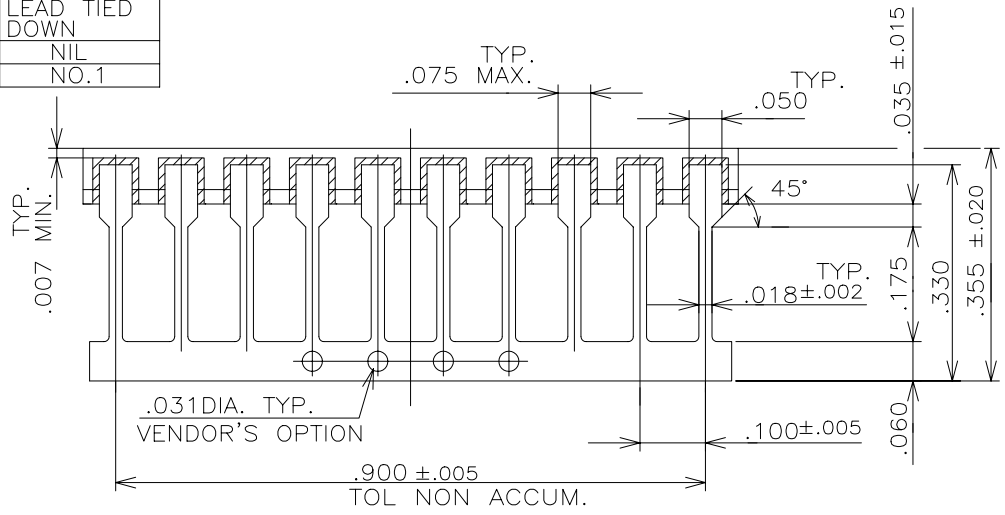


PART NO.	INDEX MARK	LEAD TIED DOWN
-01		NIL
-02		NO.1

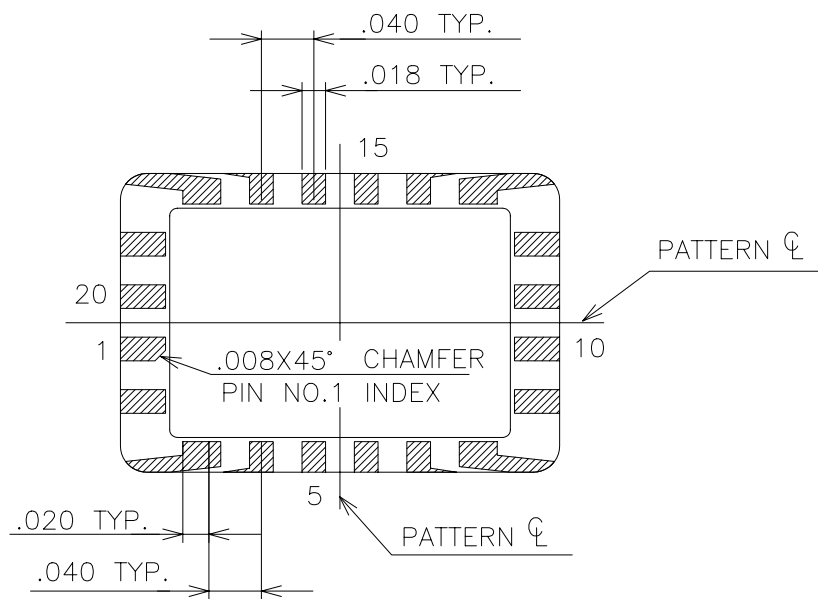


- NOTES
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
 2. SEAL AREA TO BE METALLIZED.
 3. DIE ATTACH AREA TO BE METALLIZED.
 4. LEAD RESISTANCE : 0.3 OHM MAX.



SB020G250-2	S=0 D=1
SB020G250-1	S=0 D=0

MODIFICATION	NAME				TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN	CHECKED	APPROVED	DATE
	20 LEAD SIDE BRAZED PACKAGE								
△ REDRAWN: (CONVERTED CAD DATA) CHANGED	JUN.24.'93	M.S	H.SU S.F	T.A		M.S	H.SU S.F	T.A	AUG.23.'96
	DATE	DRAWN	CHECKED	APPROVED		KYOCERA CORPORATION KYOTO JAPAN		DRAWING NO.	SHEET 1/2
								KD-76250-C	



BONDING PATTERN

MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						20 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	M.S	H.SU	T.A	AUG.23.'76
						SCALE 10 / 1	MATERIAL		S.F		
							THIRD ANGLE PROJECTION				
	CHANGED	DATE	DRAWN	CHECKED	APPROVED	 KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.		SHEET		
							KD-76250-C		2/2		